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April 2015

FGA40T65SHDF 650 V, 40 A Field Stop Trench IGBT

Features

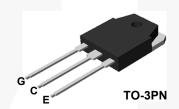
- Maximum Junction Temperature : T_J = 175°C
- Positive Temperature Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: V_{CE(sat)} = 1.45 V (Typ.) @ I_C = 40 A
- 100% of the Parts tested for I_{LM}(1)
- · High Input Impedance
- · Fast Switching
- · Tighten Parameter Distribution
- · RoHS Compliant

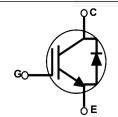
General Description

Using novel field stop IGBT technology, Fairchild's new series of field stop 3rd generation IGBTs offer superior conduction and switching performance and easy parallel operation. This device is well suited for the resonant or soft switching application such as induction heating and MWO.

Applications

· Induction Heating, MWO





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description	Description FGA40T65SHDF		Unit	
V _{CES}	Collector to Emitter Voltage		650	V	
V _{GES}	Gate to Emitter Voltage	± 20	V		
	Transient Gate to Emitter Voltage	± 30	V		
I _C	Collector Current	@ T _C = 25°C	80	Α	
'C	Collector Current	@ T _C = 100°C	40	Α	
I _{LM} (1)	Pulsed Collector Current	@ T _C = 25°C	120	Α	
I _{CM} (2)	Pulsed Collector Current		120	Α	
l _F	Diode Forward Current	@ T _C = 25°C	40	Α	
	Diode Forward Current	@ T _C = 100°C	20	Α	
I _{FM}	Pulsed Diode Maximum Forward Curr	60	Α		
P _D	Maximum Power Dissipation	@ T _C = 25°C	268	W	
LD.	Maximum Power Dissipation	@ T _C = 100°C	134	W	
T _J	Operating Junction Temperature		-55 to +175	°C	
T _{stg}	Storage Temperature Range		-55 to +175	°C	
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

- 1. V_{CC} = 400 V, V_{GE} = 15 V, I_C = 120 A, R_G = 30 Ω , Inductive Load 2. Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	FGA40T65SHDF	Unit
R _{θJC} (IGBT)	Thermal Resistance, Junction to Case, Max.	0.56	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance, Junction to Case, Max.	1.75	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity	
FGA40T65SHDF	FGA40T65SHDF	TO-3PN	Tube	-	-	30	

Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	650	-	-	V
ΔBV _{CES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0 V	-	-	250	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	± 400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I _C = 40 mA, V _{CE} = V _{GE}	4.0	5.5	7.5	V
- (-)		I _C = 40 A, V _{GE} = 15 V	-	1.45	1.81	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 40 A, V _{GE} = 15 V, T _C = 175°C	-	1.8	-	V
Dynamic C	Characteristics		-			
C _{ies}	Input Capacitance		-	1982	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	70	-	pF
C _{res}	Reverse Transfer Capacitance	1 = 1 WITZ	-	25	-	pF
Switching	Characteristics					
T _{d(on)}	Turn-On Delay Time		-	18	-	ns
T _r	Rise Time		-	27	-/	ns
T _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	64	/-	ns
T _f	Fall Time	$R_G = 6 \Omega, V_{GF} = 15 V,$	-	3	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C	-	1.22	- //	mJ
E _{off}	Turn-Off Switching Loss		-	0.44	-	mJ
E _{ts}	Total Switching Loss		-	1.66	- \	mJ
T _{d(on)}	Turn-On Delay Time		-	18	-	ns
T _r	Rise Time		-	31	-	ns
T _{d(off)}	Turn-Off Delay Time	V_{CC} = 400 V, I_{C} = 40 A, R_{G} = 6 Ω , V_{GE} = 15 V, Inductive Load, T_{C} = 175°C	-	70	-	ns
T _f	Fall Time		-	56	-	ns
E _{on}	Turn-On Switching Loss		-	1.78	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.78	-	mJ
E _{ts}	Total Switching Loss		-	2.56	-	mJ

Electrical Characteristics of the IGBT (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Qg	Total Gate Charge	V _{CE} = 400 V, I _C = 40 A, V _{GE} = 15 V	-	68	-	nC
Q _{ge}	Gate to Emitter Charge		-	12	-	nC
Q _{gc}	Gate to Collector Charge		-	25	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter		Test Conditions		Min.	Тур.	Max.	Unit
V _{FM}	Diode Forward Voltage	I _F =	20 A	T _C = 25°C	-	1.5	1.95	V
FIM				T _C = 175°C	-	1.37	-	
E _{rec}	Reverse Recovery Energy			T _C = 175°C	-	153	-	μJ
T _{rr}	Diode Reverse Recovery Time	$I_F = 20 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}$	T _C = 25°C	-	101	-	ns	
			20 A, αιρ/αι – 200 A μο	T _C = 175°C	-	238	-	
Q _{rr}	Diode Reverse Recovery Charge			T _C = 25°C	-	343	-	nC
711	y enange			T _C = 175°C	-	1493	1	

Figure 1. Typical Output Characteristics

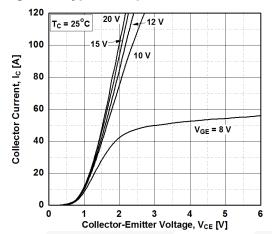


Figure 3. Typical Saturation Voltage Characteristics

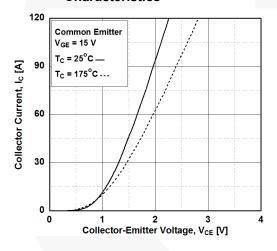


Figure 5. Saturation Voltage vs. V_{GE}

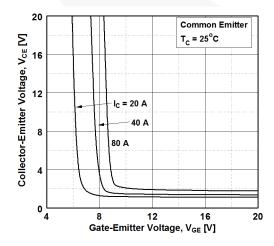


Figure 2. Typical Output Characteristics

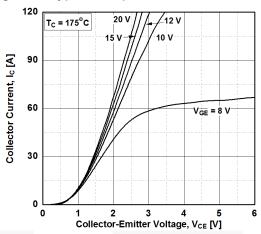


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

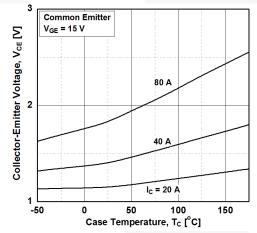


Figure 6. Saturation Voltage vs. V_{GE}

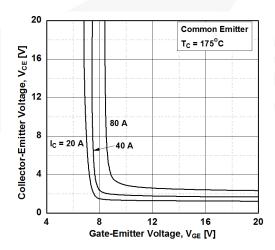


Figure 7. Capacitance Characteristics

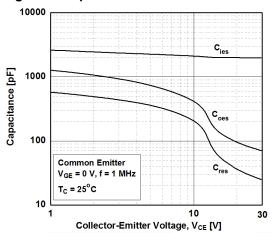


Figure 8. Gate charge Characteristics

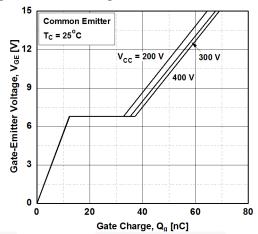


Figure 9. Turn-on Characteristics vs.
Gate Resistance

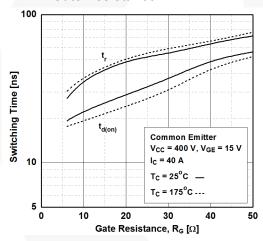


Figure 10. Turn-off Characteristics vs. Gate Resistance

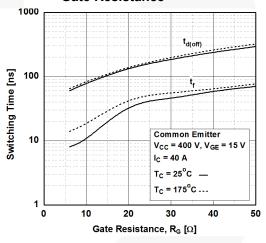


Figure 11. Switching Loss vs.

Gate Resistance

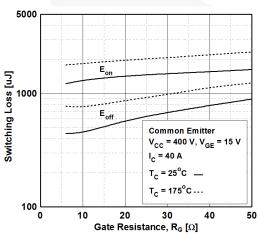


Figure 12. Turn-on Characteristics vs. Collector Current

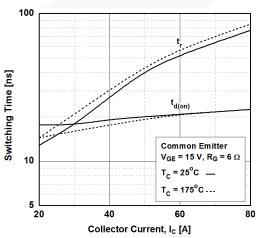


Figure 13. Turn-off Characteristics vs. Collector Current

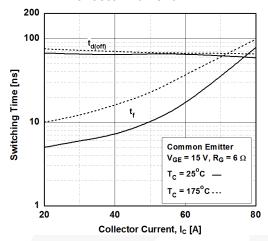


Figure 15. Load Current Vs. Frequency

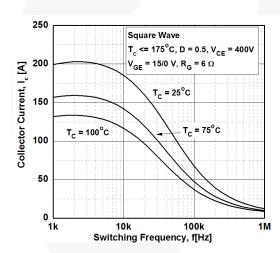


Figure 17. Forward Characteristics

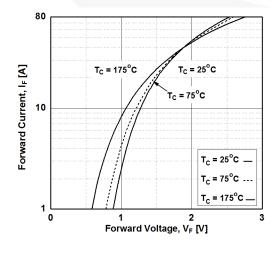


Figure 14. Switching Loss vs. Collector Current

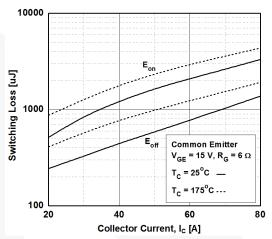


Figure 16. SOA Characteristics

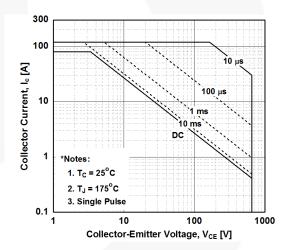


Figure 18. Reverse Recovery Current

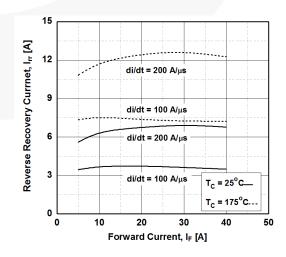


Figure 19. Reverse Recovery Time

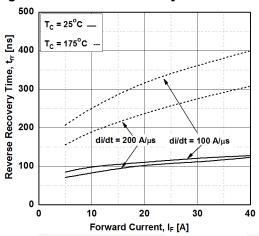


Figure 20. Stored Charge

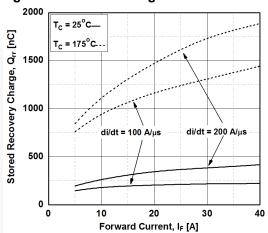


Figure 21. Transient Thermal Impedance of IGBT

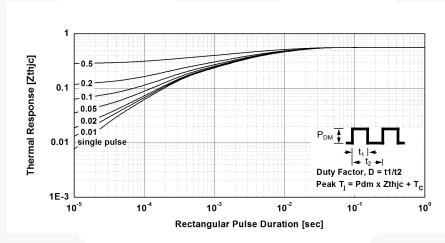
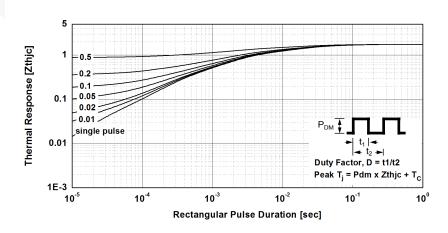
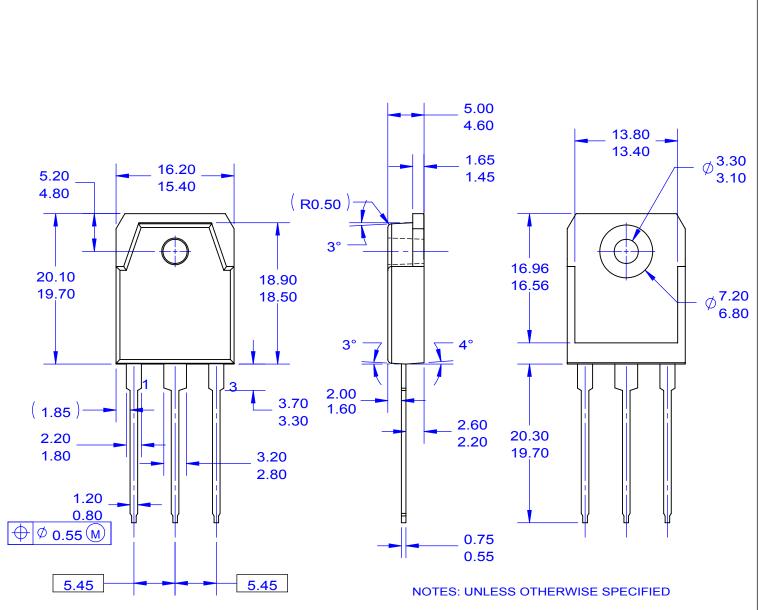
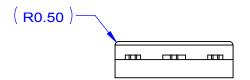


Figure 22. Transient Thermal Impedance of Diode







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